

L Number	Hits	Search Text	DB	Time stamp
1	7	("5690050" or ("5944899") or ("5735993") or ("6177646") or ("6095083") or ("5922223") or ("6077384")).PN. (118/723i).CCLS.	USPAT; US-PGPUB	2002/05/10 13:06
-	412	(156/345.48).CCLS.	USPAT; US-PGPUB	2002/05/10 13:06
-	240	(156/345.48).CCLS.	USPAT; US-PGPUB	2002/05/07 18:12
-	117	(118/723an).CCLS.	USPAT; US-PGPUB	2002/05/07 18:12
-	136	118/723i.ccls. and 156/345.48.ccls.	USPAT; EPO; JPO	2002/05/08 11:30
-	41	(118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and ((Faraday adj shield))	USPAT; EPO; JPO	2002/05/08 11:31
-	10	("4659449"   "5105761"   "5134965"   "5290993"   "5401350"   "5415728"   "5522934"   "5614055"   "5753044"   "5777289").PN.	USPAT	2002/05/08 11:50
-	5	("5681418"   "5688357"   "5688358"   "5753044"   "5777289").PN.	USPAT	2002/05/08 11:52
-	192	(118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield))	USPAT; EPO; JPO	2002/05/08 11:57
-	59310	heat near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 13:21
-	1	((resist\$3 adj heat\$3) near5 (chamber reactor)) and ((118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield)))	USPAT; EPO; JPO	2002/05/08 13:23
-	384	(resist\$3 adj heat\$3) near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 14:31
-	125	(resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition)	USPAT; EPO; JPO	2002/05/08 13:29
-	259	((resist\$3 adj heat\$3) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition))	USPAT; EPO; JPO	2002/05/08 14:05
-	12	4484063.URPN.	USPAT	2002/05/08 14:22
-	165	(heat\$3 adj wire) near5 (chamber reactor)	USPAT; EPO; JPO	2002/05/08 14:33
-	164	((heat\$3 adj wire) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor))	USPAT; EPO; JPO	2002/05/08 16:03
-	1440	118/724.ccls.	USPAT; EPO; JPO	2002/05/08 16:21
-	30	118/724.ccls. and (heat\$3 adj wire)	USPAT; EPO; JPO	2002/05/09 08:49
-	12	4958592.URPN.	USPAT	2002/05/08 16:17
-	20	118/724.ccls. and 118/723i.ccls.	USPAT; EPO; JPO	2002/05/08 16:49
-	6	("5001113"   "5365057"   "5401350"   "5556501"   "5614055"   "5865896").PN.	USPAT	2002/05/08 16:37
-	1085	c23c016/48.ipc.	EPO; JPO	2002/05/08 16:56
-	4	c23c016/48.ipc. and ((heat\$3 adj wire) (resistive adj heat) (resist\$ adj heat))	EPO; JPO	2002/05/08 16:51
-	15	c23c016/48.ipc. and "applied materials".as.	EPO; JPO	2002/05/08 16:57
-	4	5690050.URPN.	USPAT	2002/05/08 17:17
-	317	118/724.ccls. and (((heat\$3 adj element) (resist\$3 adj heat\$3) heat) near5 (chamber reactor))	USPAT; EPO; JPO	2002/05/09 10:09
-	109	156/345.37.ccls.	USPAT; EPO; JPO	2002/05/09 10:24
-	114	156/345.37.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:22
-	1963	118/725.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:23

-	23	118/725.ccls. and (((resist\$3 adj heat) (heat\$3 adj wire) near5 (substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:26
-	6	118/725.ccls. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:30
-	389	((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:28
-	2	(h011021/\$.ipc. and c23c016/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:41
-	11	c23c016/\$.ipc. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:43
-	53	(h011021/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:55
-	7941	(substrate workpiece wafer) adj conductive	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	26835	(substrate workpiece wafer) near conductive	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:29
-	85726	vapor adj deposition	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	3206	(vapor adj deposition) and ((substrate workpiece wafer) near conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:30
-	2	156/345.48 and ((substrate workpiece wafer) adj conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:31
-	9	156/345.48 and ((substrate workpiece wafer) near conductive)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 16:31